

ABSTRACT OF THE DISCLOSURE

WAFER DRYING APPARATUS AND WAFER DRYING METHOD

5 A wafer drying apparatus capable of preventing formation of a watermark is disclosed. The wafer drying apparatus includes: a conveying mechanism configured to convey a wafer in a drying chamber; an inert-gas jet nozzle disposed above the conveying mechanism and configured to form a descending jet of an inert gas; and a liquid suction
10 nozzle disposed upstream of the inert-gas jet nozzle with respect to a conveying direction of the wafer. A distance between the liquid suction nozzle and a surface of the wafer when the wafer is being conveyed by the conveying mechanism is in a range of 1 mm to 2 mm.

FIG. 2